

ABSTRACT

The substrate (10) of the present invention includes:
a first electrode (26) and a second electrode (30). The second
5 electrode (30) is formed on an insulation film (52) covering
at least a part of the first electrode (26) and electrically
connected with the first electrode (26) through a contact
hole (50) formed in the insulation film (52). The first
electrode (26) includes a laminated structure of a metal
10 film (42) and a protective film (44). An etching rate of
the metal film (42) is almost equal to an etching rate of
the protective film (44) with respect to a first etching
for forming the metal film (42) and the protective film (44).
An etching rate of the protective film (44) is almost zero
15 with respect to a second etching for forming the contact
hole (50).